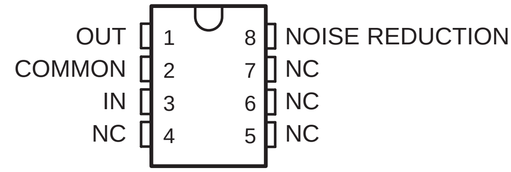
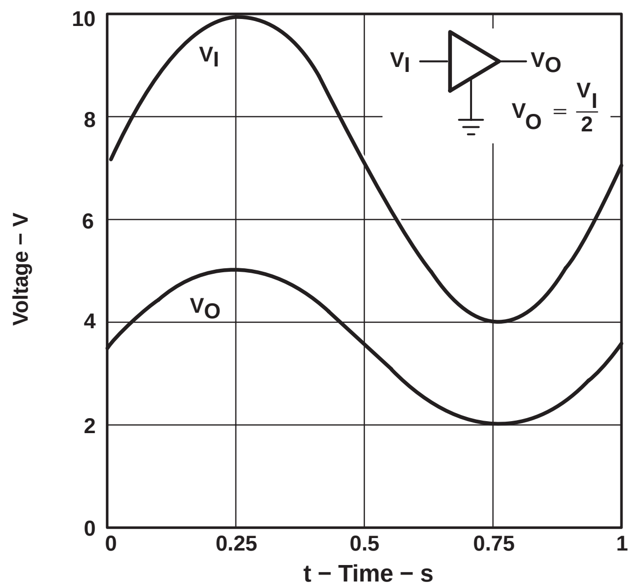
- **Qualified for Automotive Applications**
- **1/2 V_I Virtual Ground for Analog Systems**
- **Micropower Operation . . . 170 µA Typ, V_I = 5 V**
- **Wide V_I Range . . . 4 V to 40 V**
- **High Output-Current Capability**
  - **Source . . . 20 mA Typ**
  - **Sink . . . 20 mA Typ**
- **Excellent Output Regulation**
  - **−102 µV Typ at I_O = 0 to −10 mA**
  - **+49 µV Typ at I_O = 0 to +10 mA**
- **Low-Impedance Output . . . 0.0075 Ω Typ**
- **Noise Reduction Pin**

D PACKAGE
(TOP VIEW)



NC − No internal connection

INPUT/OUTPUT TRANSFER CHARACTERISTICS



description

In signal-conditioning applications utilizing a single power source, a reference voltage equal to one-half the supply voltage is required for termination of all analog signal grounds. Texas Instruments presents a precision virtual ground whose output voltage is always equal to one-half the input voltage, the TLE2426 *rail splitter*.

The unique combination of a high-performance, micropower operational amplifier and a precision-trimmed divider on a single silicon chip results in a precise V_O/V_I ratio of 0.5 while sinking and sourcing current. The TLE2426 provides a low-impedance output with 20 mA of sink and source capability while drawing less than 280 µA of supply current over the full input range of 4 V to 40 V. A designer need not pay the price in terms of board space for a conventional signal ground consisting of resistors, capacitors, operational amplifiers, and voltage references. For increased performance, the 8-pin package provides a noise-reduction pin. With the addition of an external capacitor (C_{NR}), peak-to-peak noise is reduced while line ripple rejection is improved.

Initial output tolerance for a single 5-V or 12-V system is better than 1% over the full 40-V input range. Ripple rejection exceeds 12 bits of accuracy. Whether the application is for a data acquisition front end, analog signal termination, or simply a precision voltage reference, the TLE2426 eliminates a major source of system error.

ORDERING INFORMATION†

T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 125°C	SOIC (D)	Tape and Reel	TLE2426QDRQ1	2426Q1

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.
‡ Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Continuous input voltage, V_I . . . . 40 V
Continuous filter trap voltage . . . . 40 V
Output current, I_O . . . . ±80 mA
Duration of short-circuit current at (or below) 25°C (see Note 1) . . . . unlimited
Continuous total power dissipation . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A: Q suffix . . . . −40°C to 125°C
Storage temperature range, T_{stg} . . . . −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D package . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	1102 mV	10.3 mW/°C	638.5 mW	484 mW	72.1 mW

recommended operating conditions

	MIN	MAX	UNIT
Input voltage, V_I	4	40	V
Operating free-air temperature, T_A	−40	125	°C

electrical characteristics at specified free-air temperature, V_I = 5 V, I_O = 0 (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A†	MIN	TYP	MAX	UNIT
Output voltage	V_I = 4 V		25°C	1.98	2	2.02	V
	V_I = 5 V			2.48	2.5	2.52	
	V_I = 40 V			19.8	20	20.2	
	V_I = 5 V		Full range	2.465		2.535	
Temperature coefficient of output voltage			Full range		25		ppm/°C
Supply current	No load	V_I = 5 V	25°C		170	300	μA
		V_I = 4 to 40 V	Full range			400	
Output voltage regulation (sourcing current)‡	I_O = 0 to −10 mA		25°C		−0.102	±0.7	mV
			Full range			±10	
	I_O = 0 to −20 mA		25°C		−0.121	±1.4	
Output voltage regulation (sinking current)‡	I_O = 0 to 10 mA		25°C		0.049	±0.5	mV
	I_O = 0 to 8 mA		Full range			±10	
	I_O = 0 to 20 mA		25°C		0.175	±1.4	
Output impedance‡			25°C		7.5	22.5	mΩ
Noise-reduction impedance			25°C		110		kΩ
Short-circuit current	Sinking current,	V_O = 5 V	25°C		26		mA
	Sourcing current,	V_O = 0			−47		
Output noise voltage, rms	f = 10 Hz to 10 kHz	C_{NR} = 0	25°C		120		μV
		C_{NR} = 1 μF			30		
Output voltage current step response	V_O to 0.1%, I_O = ±10 mA	C_L = 0	25°C		290		μs
		C_L = 100 pF			275		
	V_O to 0.01%, I_O = ±10 mA	C_L = 0	25°C		400		
		C_L = 100 pF			390		
Step response	V_I = 0 to 5 V, V_O to 0.1%	C_L = 100 pF	25°C		20		μs
	V_I = 0 to 5 V, V_O to 0.01%				120		

† Full range is −40°C to 125°C.
‡ The listed values are not production tested.

electrical characteristics at specified free-air temperature, V_I = 12 V, I_O = 0 (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A†	MIN	TYP	MAX	UNIT
Output voltage	V_I = 4 V		25°C	1.98	2	2.02	V
	V_I = 12 V			5.95	6	6.05	
	V_I = 40 V			19.8	20	20.2	
	V_I = 12 V		Full range	5.925		6.075	
Temperature coefficient of output voltage			Full range		35		ppm/°C
Supply current	No load	V_I = 12 V	25°C		195	300	µA
		V_I = 4 to 40 V	Full range			400	
Output voltage regulation (sourcing current)‡	I_O = 0 to −10 mA		25°C		−1.48	±10	mV
			Full range			±10	
	I_O = 0 to −20 mA		25°C		−3.9	±10	
Output voltage regulation (sinking current)‡	I_O = 0 to 10 mA		25°C		2.27	±10	mV
	I_O = 0 to 8 mA		Full range			±10	
	I_O = 0 to 20 mA		25°C		4.3	±10	
Output impedance‡			25°C		7.5	22.5	mΩ
Noise-reduction impedance			25°C		110		kΩ
Short-circuit current	Sinking current,	V_O = 12 V	25°C		31		mA
	Sourcing current,	V_O = 0			−70		
Output noise voltage, rms	f = 10 Hz to 10 kHz	C_{NR} = 0	25°C		120		µV
		C_{NR} = 1 µF			30		
Output voltage current step response	V_O to 0.1%, I_O = ±10 mA	C_L = 0	25°C		290		µs
		C_L = 100 pF			275		
	V_O to 0.01%, I_O = ±10 mA	C_L = 0	25°C		400		
		C_L = 100 pF			390		
Step response	V_I = 0 to 12 V, V_O to 0.1%	C_L = 100 pF	25°C		12		µs
	V_I = 0 to 12 V, V_O to 0.01%				120		

† Full range is −40°C to 125°C.
‡ The listed values are not production tested.

TYPICAL CHARACTERISTICS

Table Of Graphs

		FIGURE
Output voltage	Distribution	1, 2
Output voltage change	vs Free-air temperature	3
Output voltage error	vs Input voltage	4
Input bias current	vs Input voltage	5
	vs Free-air temperature	6
Output voltage regulation	vs Output current	7
Output impedance	vs Frequency	8
Short-circuit output current	vs Input voltage	9, 10
	vs Free-air temperature	11, 12
Ripple rejection	vs Frequency	13
Spectral noise voltage density	vs Frequency	14
Output voltage response to output current step	vs Time	15
Output voltage power-up response	vs Time	16
Output current	vs Load capacitance	17

TYPICAL CHARACTERISTICS†

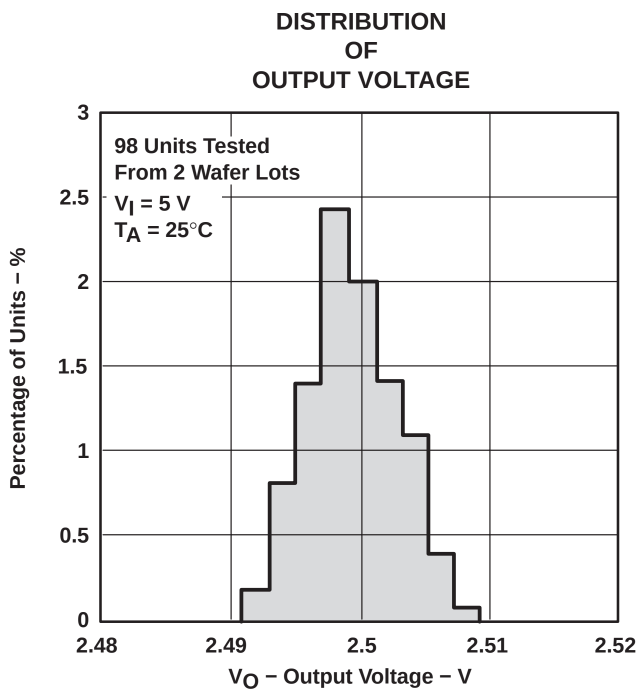


Figure 1

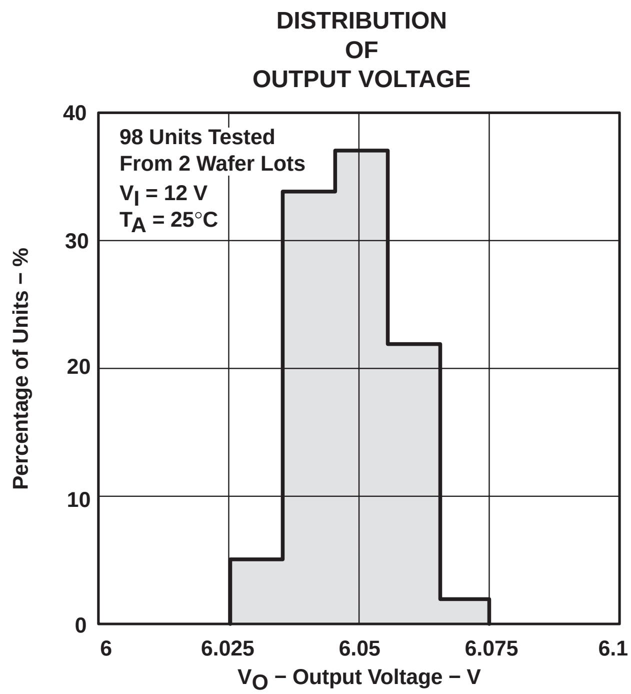


Figure 2

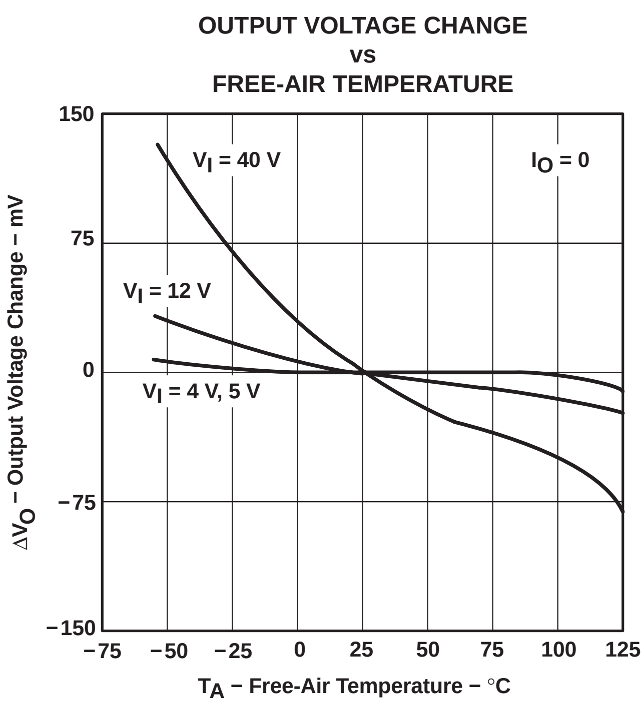


Figure 3

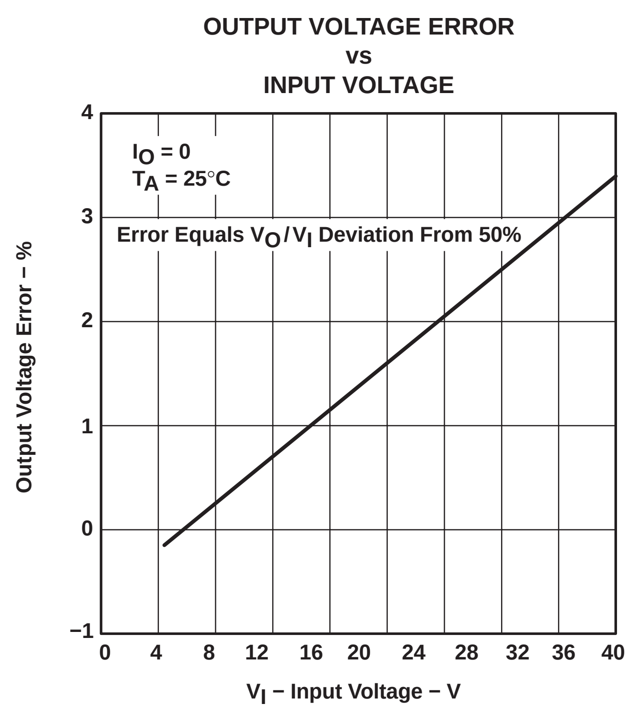


Figure 4

† Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

INPUT BIAS CURRENT vs INPUT VOLTAGE

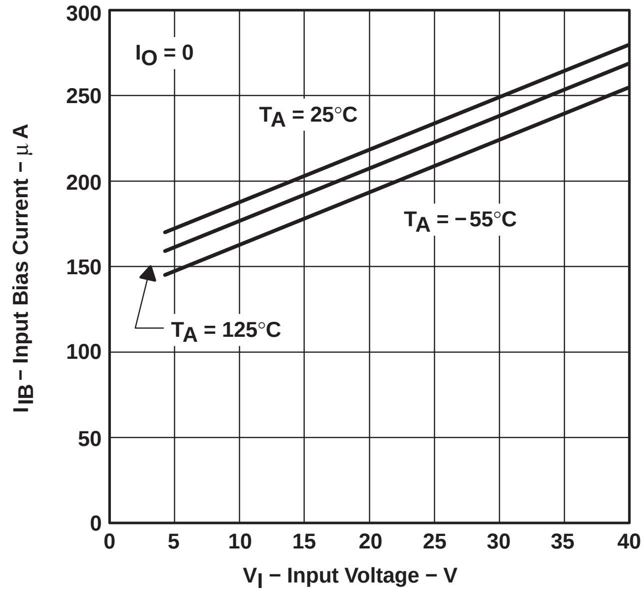


Figure 5

INPUT BIAS CURRENT vs FREE-AIR TEMPERATURE

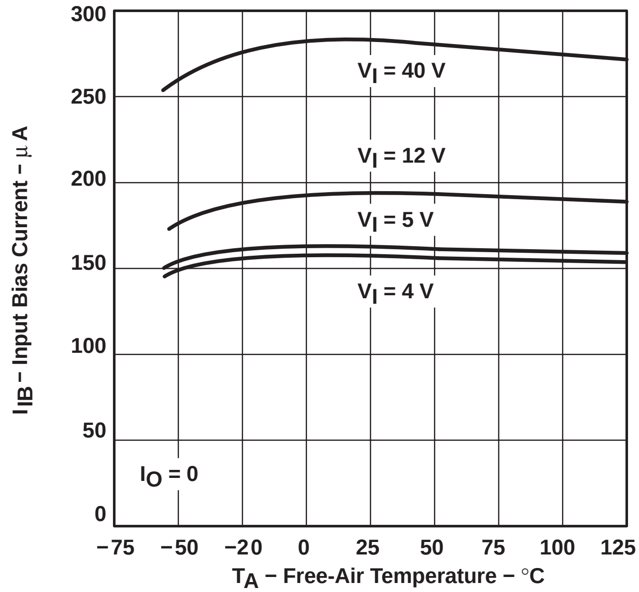


Figure 6

OUTPUT VOLTAGE REGULATION vs OUTPUT CURRENT

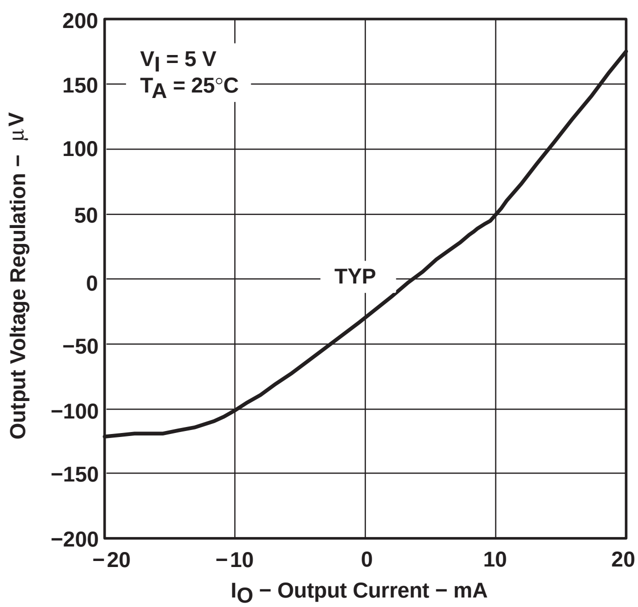


Figure 7

OUTPUT IMPEDANCE vs FREQUENCY

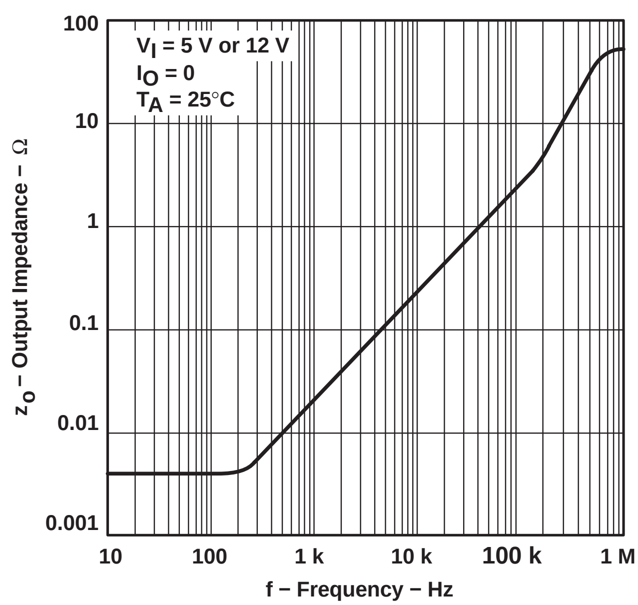


Figure 8

† Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

SHORT-CIRCUIT OUTPUT CURRENT
vs
INPUT VOLTAGE

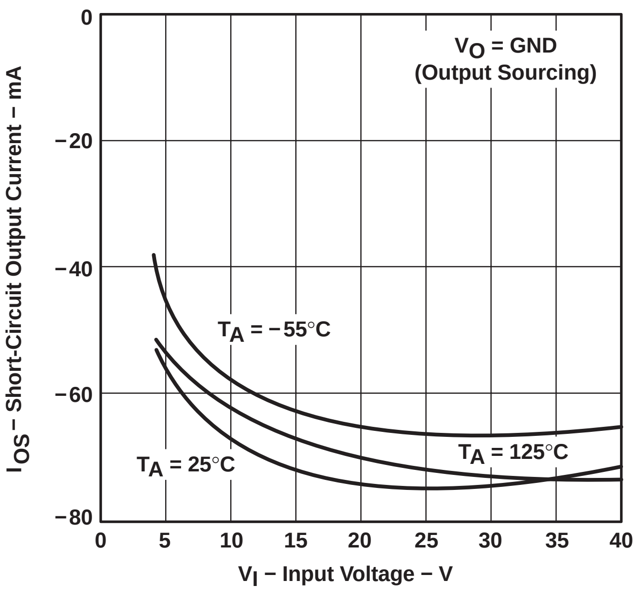


Figure 9

SHORT-CIRCUIT OUTPUT CURRENT
vs
INPUT VOLTAGE

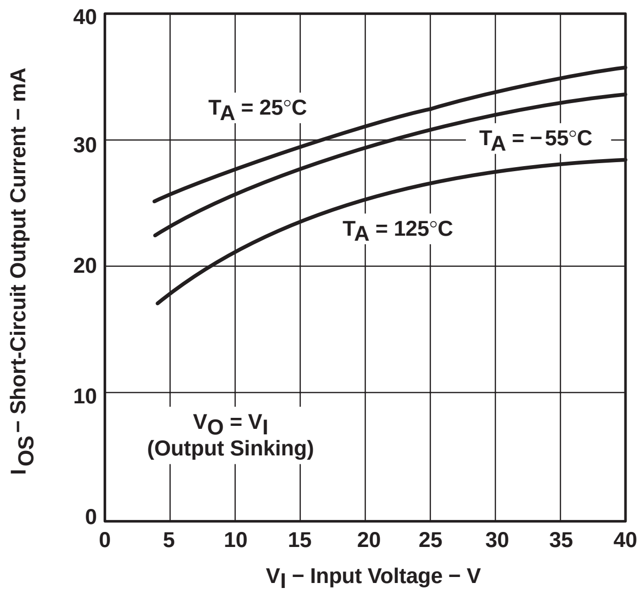


Figure 10

SHORT-CIRCUIT OUTPUT CURRENT
vs
FREE-AIR TEMPERATURE

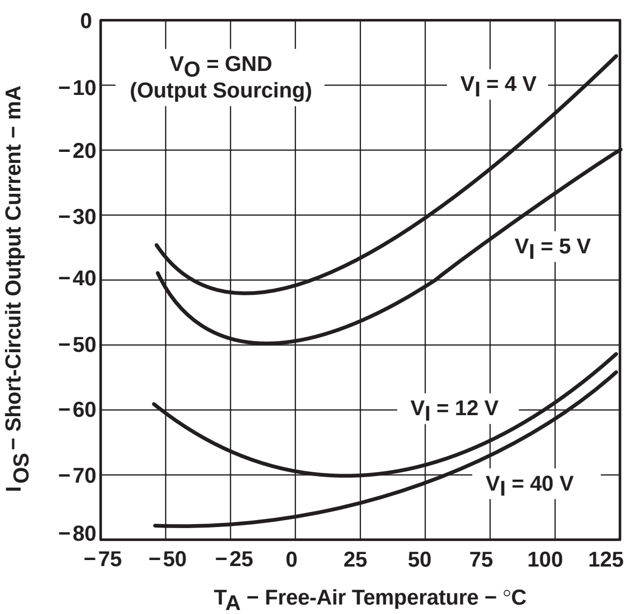


Figure 11

SHORT-CIRCUIT OUTPUT CURRENT
vs
FREE-AIR TEMPERATURE

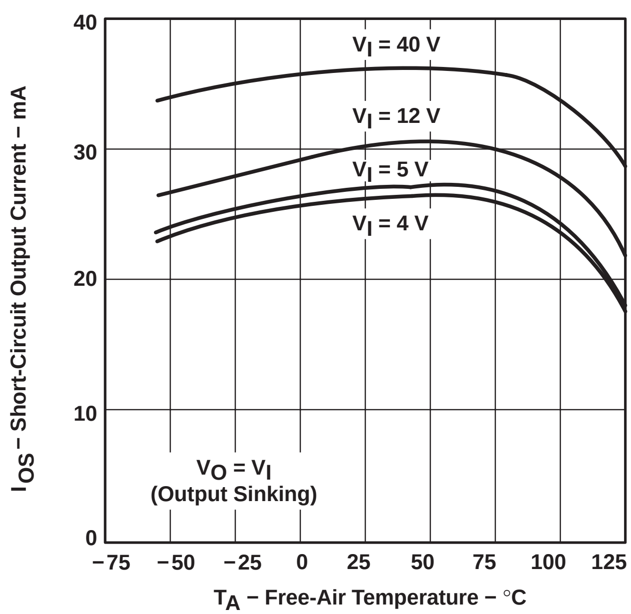


Figure 12

† Data at high and low temperatures are applicable within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

RIPPLE REJECTION
vs
FREQUENCY

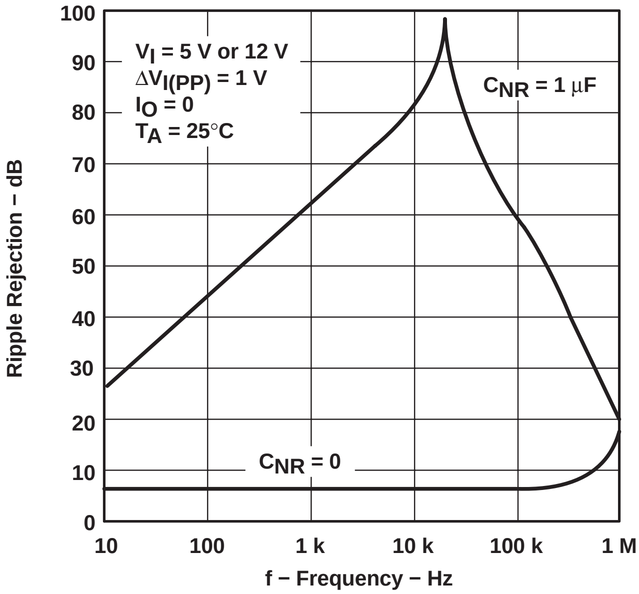


Figure 13

SPECTRAL NOISE VOLTAGE DENSITY
vs
FREQUENCY

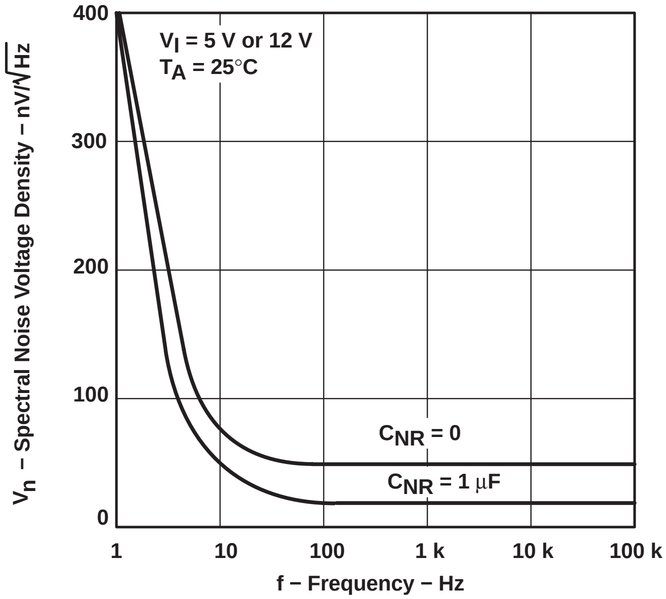


Figure 14

OUTPUT VOLTAGE RESPONSE
TO OUTPUT CURRENT STEP

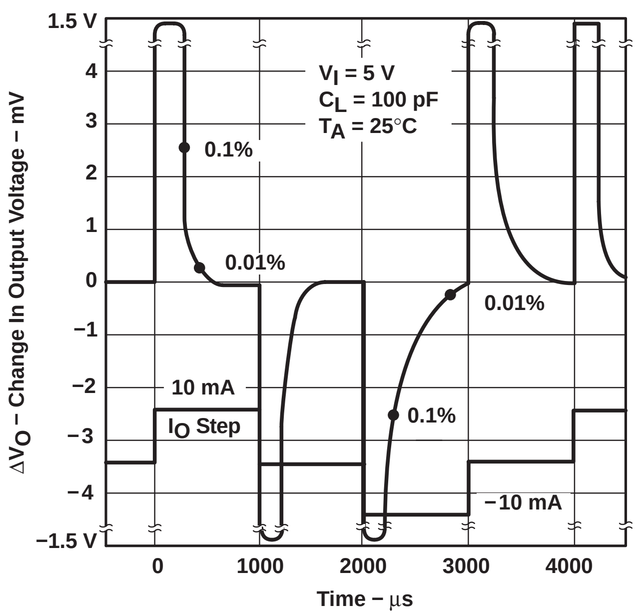


Figure 15

OUTPUT VOLTAGE POWER-UP RESPONSE

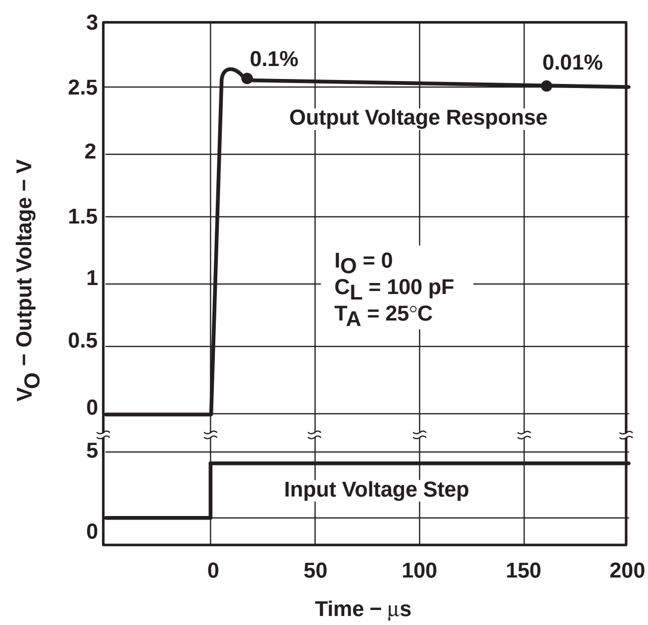


Figure 16

TYPICAL CHARACTERISTICS

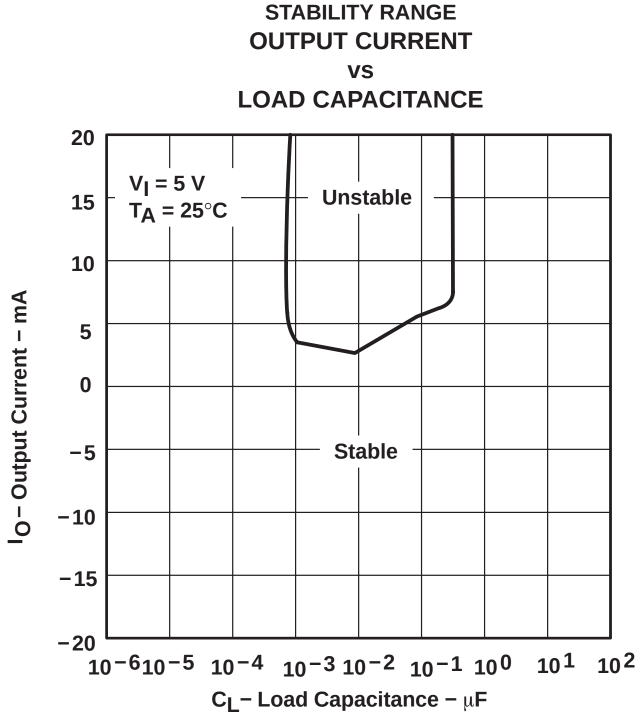


Figure 17

MACROMODEL INFORMATION

```
*   TLE2426 OPERATIONAL AMPLIFIER “MACROMODEL” SUBCIRCUIT
*   CREATED USING PARTS RELEASE 4.03 ON 08/21/90 AT 13:51
*   REV (N/A)     SUPPLY VOLTAGE: 5 V
*   CONNECTIONS:      FILTER
                      |   INPUT
*                     |   |   COMMON
*                     |   |   |   OUTPUT
*                     |   |   |   |
.SUBCKT TLE2426       1   3   4   5
```

```
   C1     11  12  21.66E-12
   C2      6   7  30.00E-12
   C3     87   0  10.64E-9
   CPSR   85  86  15.9E-9
   DCM+   81  82  DX
   DCM-   83  81  DX
   DC      5  53  DX
   DE     54   5  DX
   DLP    90  91  DX
   DLN    92  90  DX
   DP      4   3  DX
   ECMR   84  99  (2,99) 1
   EGND   99   0  POLY(2)   (3,0) (4,0)   0   .5  .5
   EPSR   85   0  POLY(1)   (3,4)  -16.22E-6 3.24E-6
   ENSE   89   2  POLY(1)   (88,0) 120E-6 1
   FB      7  99  POLY(6)   VB  VC  VE  VLP VLN VPSR 0 74.8E6 -10E6  10E6   10E6   -10E6  74E6
   GA      6   0  11  12  320.4E-6
   GCM     0   6  10  99  1.013E-9
   GPSR   85  86  (85,86)   100E-6
   GRC1    4  11  (4,11) 3.204E-4
   GRC2    4  12  (4,12) 3.204E-4
   GRE1   13  10  (13,10)   1.038E-3
   GRE2   14  10  (14,10)   1.038E-3
   HLIM   90   0  VLIM   1K
   HCMR   80   1  POLY(2)   VCM+   VCM-   0   1E2    1E2
   IRP     3   4  146E-6
   IEE     3  10  DC  24.05E-6
   IIO     2   0  .2E-9
   I1     88   0  1E-21
   Q1     11  89  13  QX
   Q2     12  80  14  QX
   R2      6   9  100.0E3
   RCM    84  81  1K
   REE    10  99   8.316E6
   RN1    87   0   2.55E8
   RN2    87  88  11.67E3
   RO1     8   5  63
   RO2     7  99  62
   VCM+   82  99  1.0
   VCM-   83  99  -2.3
   VB      9   0  DC  0
   VC      3  53  DC  1.400
   VE     54   4  DC  1.400
   VLIM    7   8  DC  0
   VLP    91   0  DC  30
   VLN     0  92  DC  30
   VPSR    0  86  DC  0
   RFB     5   2  1K
   RIN1    3   1  220K
   RIN2    1   4  220K
.MODEL DX  D(IS=800.OE-18)
.MODEL QX  PNP(IS=800.OE-18 BF=480)
.ENDS
```

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TLE2426QDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLE2426QDRQ1	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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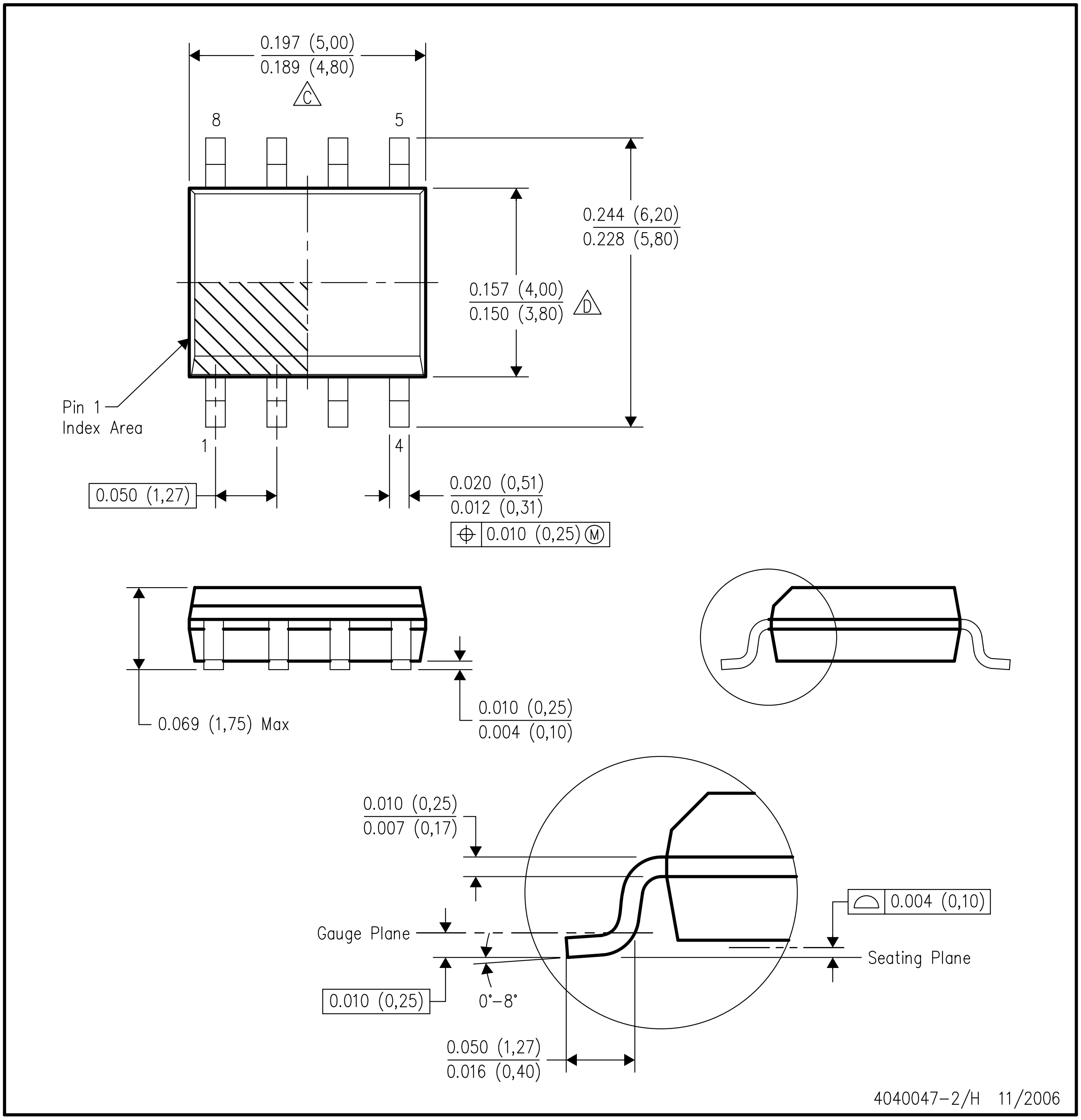
OTHER QUALIFIED VERSIONS OF TLE2426-Q1 :
- Catalog: TLE2426
- Enhanced Product: TLE2426-EP

NOTE: Qualified Version Definitions:
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS–012 variation AA.

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